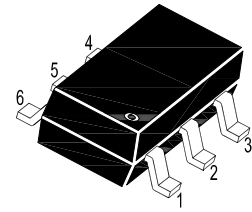
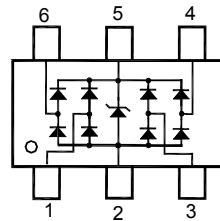


ESDLC0545D

4-Channel Low Capacitance TVS Array



1. I/O1 2. GND 3. I/O2
4. I/O3 5. VCC 6. I/O4
Marking Code: F4
SOT-26 Plastic package

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Peak Pulse Current ($t_p = 8/20 \mu\text{s}$)	I_{PP}	5	A
Peak Pulse Power ($t_p = 8/20 \mu\text{s}$)	P_{PK}	75	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	± 18 ± 12	KV
Operation Temperature Range	T_j	- 55 to + 125	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 55 to + 150	$^\circ\text{C}$

Characteristics at $T_a = 25^\circ\text{C}$

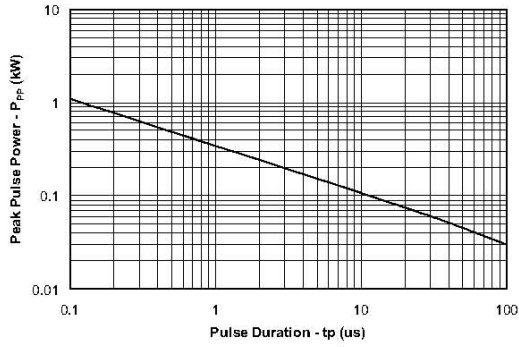
Parameter	Symbol	Min.	Max.	Unit
Reverse Stand-Off Voltage at Pin 1, 3, 4 or 6 to Gnd	V_{RWM}	-	5	V
Reverse Breakdown Voltage at $I_t = 1 \text{ mA}$, Pin 1, 3, 4 or 6 to Gnd	$V_{(BR)R}$	6.5	11	V
Reverse Current at $V_{RWM} = 5 \text{ V}$, Pin 1, 3, 4 or 6 to Gnd	I_R	-	0.1	μA
Clamping Voltage at $I_{PP} = 1 \text{ A}$, $t_p = 8/20 \mu\text{s}$, Pin 1, 3, 4 or 6 Pin to Pin Gnd	V_C	-	12	V
Clamping Voltage at $I_{PP} = 5 \text{ A}$, $t_p = 8/20 \mu\text{s}$, Pin 1, 3, 4 or 6 Pin to Pin Gnd	V_C	-	15	V
Junction Capacitance at $V_R = 0 \text{ V}$, $f = 1 \text{ MHz}$, Pin 1, 3, 4 or 6 I/O Pin to Pin Gnd at $V_R = 0 \text{ V}$, $f = 1 \text{ MHz}$, Between I/O Pins	C_j	-	0.6 0.4	pF

TOP DYNAMIC

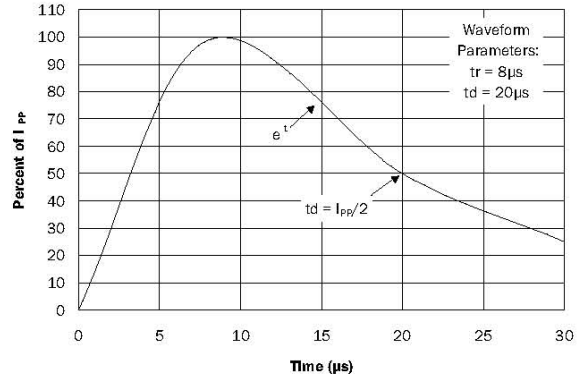


Dated: 07/01/2016 Rev: 01

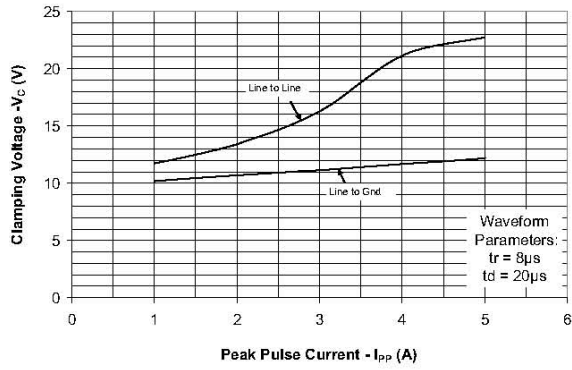
Non-Repetitive Peak Pulse Power vs. Pulse Time



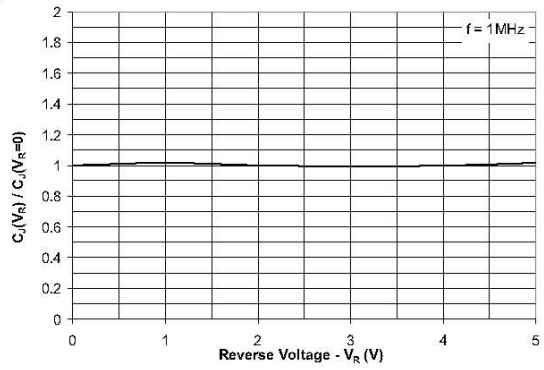
Pulse Waveform



Clamping Voltage vs. Peak Pulse Current



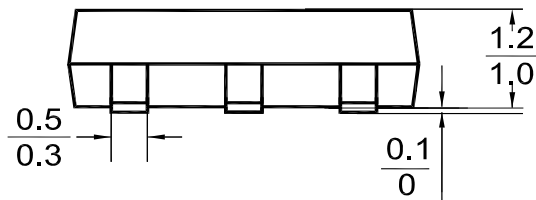
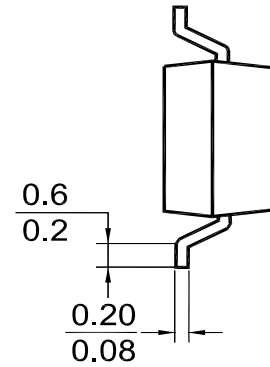
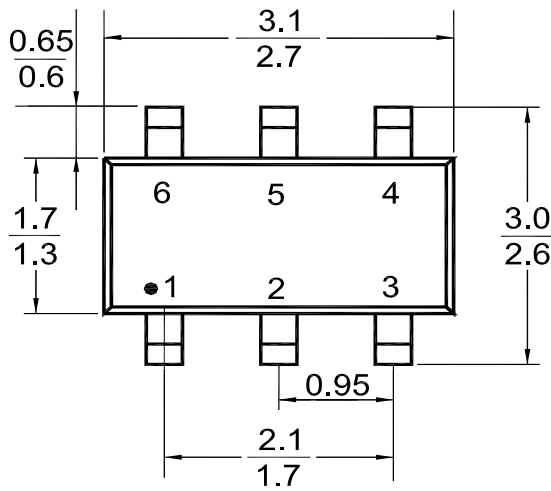
Normalized Capacitance vs. Reverse Voltage



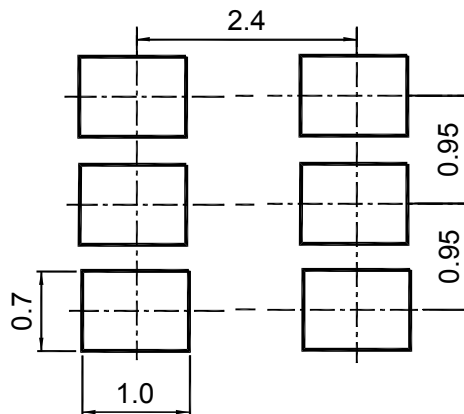
ESDLC0545D

Package Outline Dimensions (Units: mm)

SOT-26



Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-26	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

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